Affinity Gold 3.0

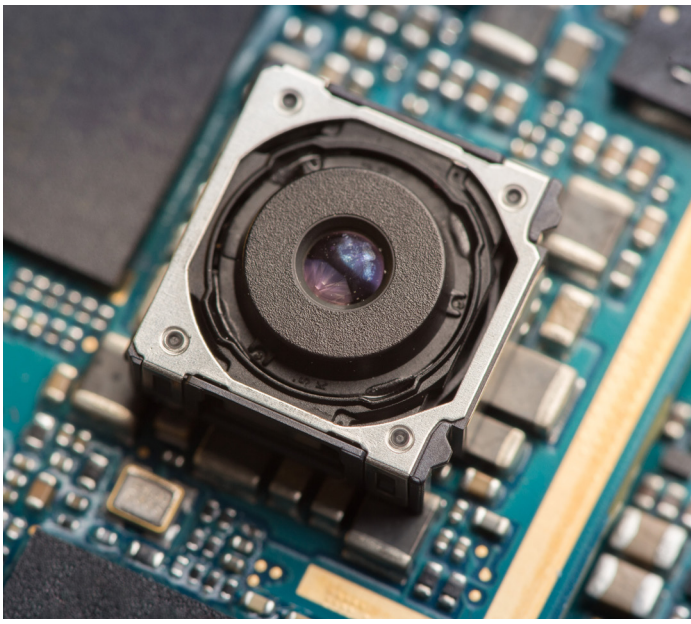
Corrosion Elimination for Advanced ENIG / ENEPIG Systems

Highest Reliability for Most Challenging Applications

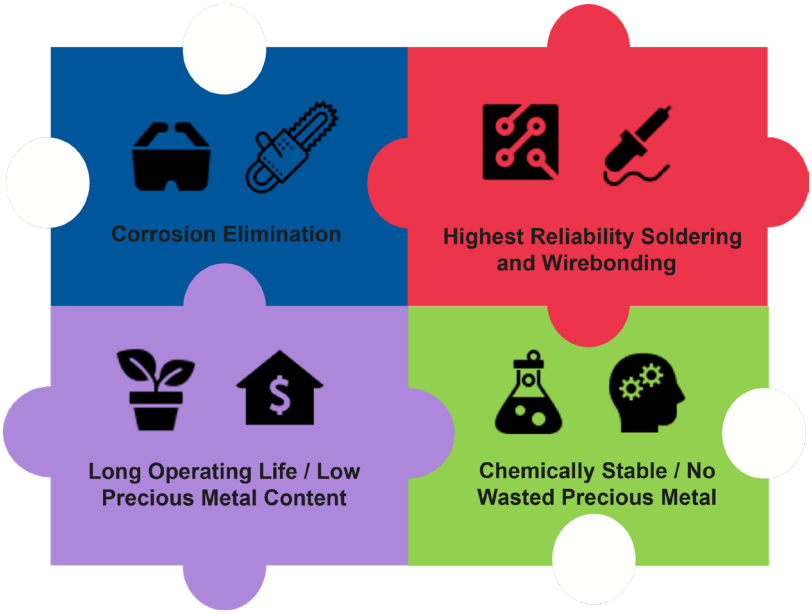
Affinity Gold 3.0 is a gold plating solution for use in ENIG and ENEPIG applications that demand the highest levels of reliability.

Affinity Gold 3.0 delivers increased gold thickness capability over traditional systems, with an absence of corrosion all from a chemically stable electrolyte with low metal content and exceptional working life.

Corrosion elimination allows confidence in product quality and ensures the highest reliability soldering and wirebonding performance even after prolonged product shelf life.



KEY FEATURES



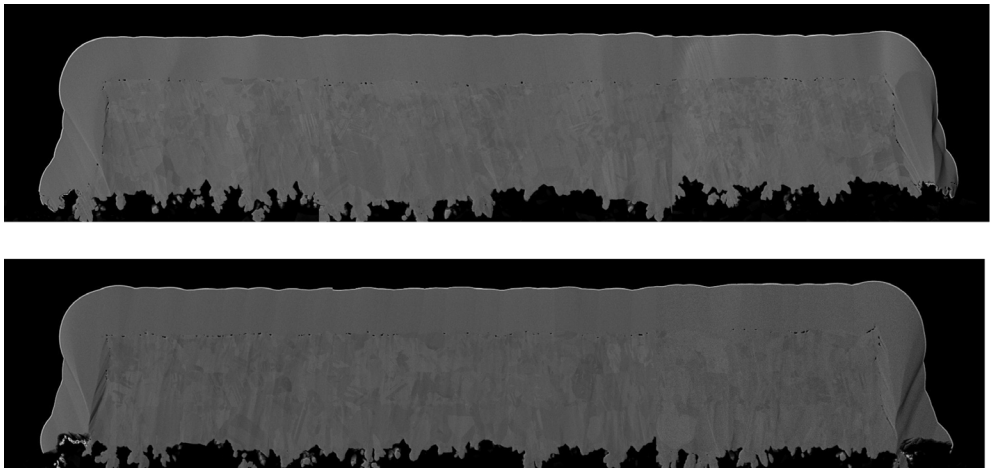
MacDermid Alpha ELECTRONICS SOLUTIONS

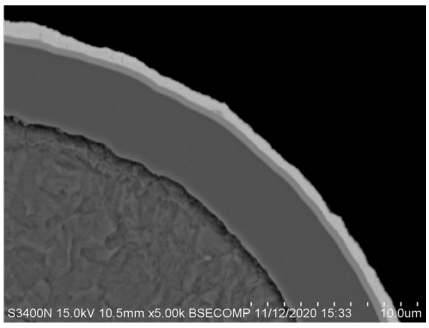
Affinity Gold 3.0

Hybrid Gold Deposition

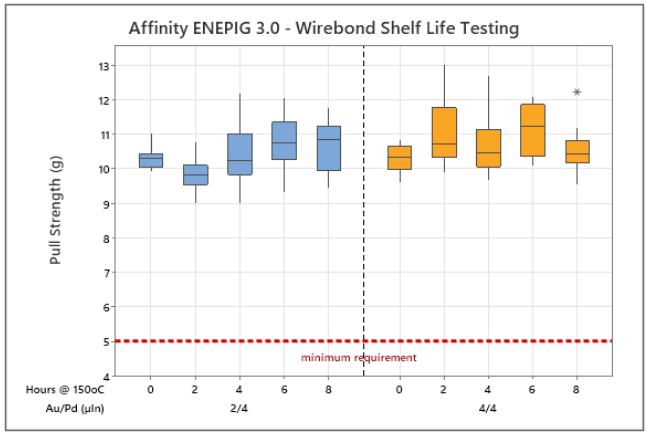
Corrosion Observations Reduced to Zero

Affinity **Gold 3.0**'s hybrid gold deposition mechanism allows thicker gold deposition independently of palladium thickness allowing increased ENEPIG production capabilities, with significant reduction in galvanic displacement properties providing unrivaled corrosion conformance to all industry specifications.

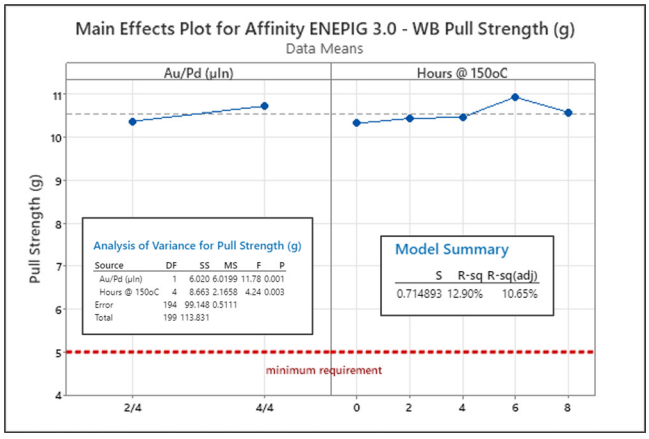




Sustainable Technology for OEMs and Fabricators



Boxplot of ENEPIG gold wirebonding with both two and four microinches of gold after accelerated aging



Statistical analysis of gold wirebonding after accelerated aging showing stable performance at both gold thicknesses over long storage time

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